

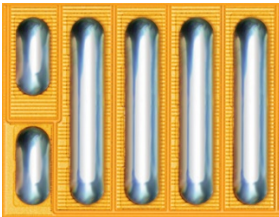
# EPCDESIGNTOOL\_MD-EM

## Mechanical Die for Electromigration Testing

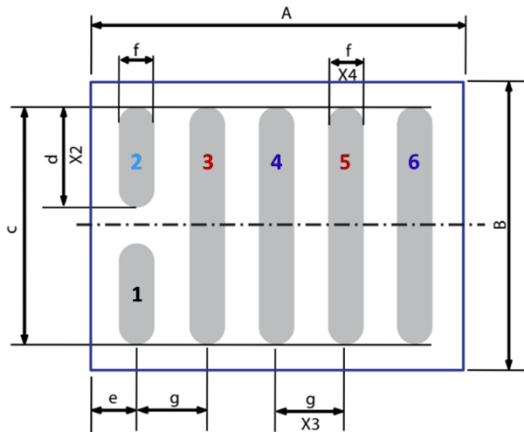
EPCDESIGNTOOL\_MD-EM are sized equivalent to EPC device [EPC2016C](#) with die size 2.1 mm x 1.6 mm.

These devices have internal metal layers shorted for electromigration reliability testing.

**Figure 1: Die Photo for EPCDESIGNTOOL\_MD-EM**



**Figure 2: Die Outline (Solder Bar View)**



DIM	MICROMETERS		
	MIN	Nominal	MAX
A	2076	2106	2136
B	1602	1632	1662
c	1379	1382	1385
d	577	580	583
e	235	250	265
f	195	200	205
g	400	400	400

**Pad 1 is Gate;**

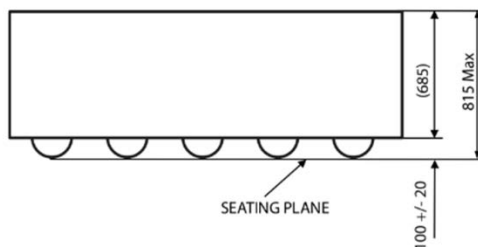
**Pads 3, 5 are Drain**

**Pads 4, 6 are Source**

**Pad 2 is Substrate**

**NOTE: Drain and Source are internally shorted at Metal 1 to create a metal resistor**

**Figure 3: Side View**



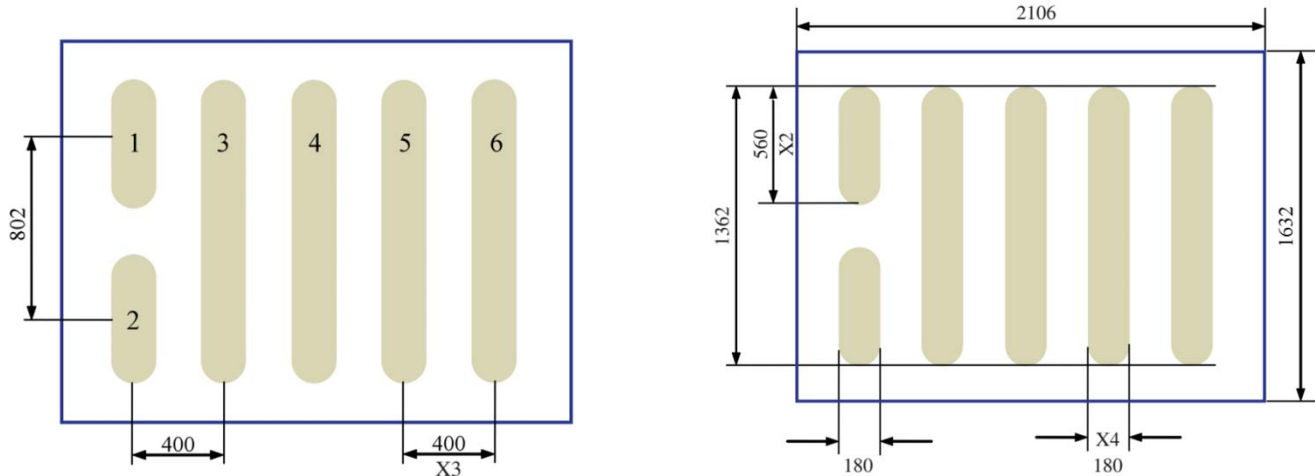
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**Figure 4: Recommended Land Pattern (units in  $\mu\text{m}$ )**

Land pattern is solder mask defined. Solder mask opening is  $180\ \mu\text{m}$ .

Recommended stencil should be 4mil ( $100\ \mu\text{m}$ ) thick, must be laser cut,

Stencil opening can be per the bump drawing.



**Pad 1 is Gate;**

**Pads 3, 5 are Drain**

**Pads 4, 6 are Source**

**Pad 2 is Substrate**

Additional assembly resources available at [epc-co.com/epc/DesignSupport/AssemblyBasics.aspx](http://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx)

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